

# Samjid H Mannan

## List of Publications by Year in descending order

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Version: 2024-02-01

30  
papers

753  
citations

759233

12  
h-index

794594

19  
g-index

30  
all docs

30  
docs citations

30  
times ranked

656  
citing authors

#	ARTICLE	IF	CITATIONS
1	A review: On the development of low melting temperature Pb-free solders. <i>Microelectronics Reliability</i> , 2014, 54, 1253-1273.	1.7	347
2	Review of silver nanoparticle based die attach materials for high power/temperature applications. <i>Microelectronics Reliability</i> , 2017, 70, 1-11.	1.7	156
3	Synthesis and characterization of gold nanoshells using poly(diallyldimethyl ammonium chloride). <i>Colloids and Surfaces A: Physicochemical and Engineering Aspects</i> , 2008, 329, 134-141.	4.7	27
4	Thermally stable high temperature die attach solution. <i>Materials and Design</i> , 2016, 89, 1310-1314.	7.0	25
5	Microstructural evolution of sintered silver at elevated temperatures. <i>Microelectronics Reliability</i> , 2016, 63, 125-133.	1.7	22
6	High bond strength Cu joints fabricated by rapid and pressureless in situ reduction-sintering of Cu nanoparticles. <i>Materials Letters</i> , 2020, 276, 128260.	2.6	21
7	Disabling of Nanoparticle Effects at Increased Temperature in Nanocomposite Solders. <i>Journal of Electronic Materials</i> , 2012, 41, 1907-1914.	2.2	20
8	Cross-Section Preparation for Solder Joints and MEMS Device Using Argon Ion Beam Milling. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , 2009, 32, 265-271.	1.4	17
9	Quasi-in-situ observation of the grain growth and grain boundary movement in sintered Cu nanoparticle interconnects. <i>Acta Materialia</i> , 2022, 236, 118135.	7.9	17
10	Tunable Ultra-high Aspect Ratio Nanorod Architectures grown on Porous Substrate via Electromigration. <i>Scientific Reports</i> , 2016, 6, 22272.	3.3	15
11	Low temperature Cu joining by in situ reduction-sintering of CuO nanoparticle for high power electronics. <i>Advanced Powder Technology</i> , 2020, 31, 4135-4144.	4.1	15
12	Study of intermetallic crystal growth between Nb and molten 52In-48Sn solder. <i>Journal of Electronic Materials</i> , 2005, 34, 125-131.	2.2	14
13	Stereoscopic Nanoscale-Precision Growth of Free-Standing Silver Nanorods by Electron Beam Irradiation. <i>Journal of Physical Chemistry C</i> , 2016, 120, 20310-20314.	3.1	10
14	Synthesis of palladium nanoshell using a layer-by-layer technique. <i>Journal of Nanoparticle Research</i> , 2010, 12, 1489-1494.	1.9	9
15	Limitations of nanoparticle enhanced solder pastes for electronics assembly. , 2012, , .		8
16	Nanoparticle Enhanced Solders for High Temperature Environments. , 2007, , .		6
17	Electronics Assembly and High Temperature Reliability Using Sn-3.8Ag-0.7Cu Solder Paste With Zn Additives. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2013, 3, 1786-1793.	2.5	6
18	Interfacial Reaction Between Molten Sn-Bi Based Solders and Electroless Ni-P Coatings for Liquid Solder Interconnects. <i>IEEE Transactions on Components and Packaging Technologies</i> , 2008, 31, 574-585.	1.3	5

#	ARTICLE	IF	CITATIONS
19	Multi-physics computer simulation of the electromigration phenomenon. , 2011, , .		3
20	Ultra-Stable Sintered Silver Die Attach for Demanding High-Power/Temperature Applications. IEEE Transactions on Device and Materials Reliability, 2017, 17, 795-798.	2.0	3
21	Failure Mechanisms of Dummy IGBT Assemblies Constructed using Liquid In-Sn/Nb System. , 2007, , .		2
22	Pressure free sintering of silver nanoparticles to silver substrate using weakly binding ligands. , 2012, , .		2
23	Analysis of jamming networks in sheared suspensions. Journal of Rheology, 2006, 50, 239-258.	2.6	1
24	Arresting high-temperature microstructural evolution inside sintered silver. Journal of Materials Science: Materials in Electronics, 2019, 30, 463-474.	2.2	1
25	Sintered Silver Die Attach with Extreme Thermal Stability for Extreme and Dynamic Environments. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2017, 2017, 000168-000176.	0.2	1
26	Nanoparticle Enhanced Solders for Increased Solder Reliability. Materials Research Society Symposia Proceedings, 2012, 1424, 115.	0.1	0
27	Evaluation of the Morphological, Electrical, and Mechanical Properties of Silver Nanopastes. Journal of Testing and Evaluation, 2015, 43, 1020-1027.	0.7	0
28	Electromigration Phenomena in Sintered Nanoparticle Ag Systems Under High Current Density. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2015, 2015, 000059-000063.	0.2	0
29	Internal Structure Refinement of Porous Sintered Silver via Electromigration. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2016, 2016, 000190-000195.	0.2	0
30	Comparative study of how additives affect sintered silver microstructure in die-attach applications. Additional Conferences (Device Packaging HiTEC HiTEN & CICMT), 2019, 2019, 000061-000065.	0.2	0